| REACTOR TOP-DOWN VIEW O hPa Reactor Pressure | | Platform Metrics 25/25 0 °C Wofers Reactor Temp | O hPa O scom IMS Pressure IMS Play | V1 Closed V2 Closed | ber ↓ Lagout ⊕ | |
|---|----------------------------------|--|---------------------------------------|------------------------|--------------------------|------|
| | | Source Status | 12 Empty Source | 0 sccm MPC100 | Abert X Gened | E |
| | ALD1 | 21 PeoSelution Bottle Temperature 0 °C | Empty Source . | 0 scom MFC200 | Create gab | 1111 |
| VCEA | VCE B | 3.1 PiceHot Bottle Temperature 0 °C Valve Temperature 0 °C | 32 Empty Source | 0 sccm M/C300 | Schedder State | - |
| VCEA | CE B 5/25 0 hPa | 4.1 Pea5olation Bottle Temperature 0 °C | Empty Source | 0 sccm LIFC400 | Cennut Disolie Job | _ |
| | Vafers Pressure Vent and Lood | 5.1 Prosolution Bottle Temperature 0 *C | 52 Piccione - 62 Piccione | o seem MFCS00 | Monual | : |
| Evacuate and Map | Evocuate and Map | 61 Empty Searce | • | sccm | | ۰. |
| Advanced functions Dummy Handling | VCE Manual Commands | 2.1 Emply Source | | A 2 | | |
| 0= jobs System | Redpes D | atalog Setup | icesun | Alarms Help | | |
| | | P | | | | |

PicoOS[™] operating system and process control software is specifically developed by Picosun's own in-house software team for the company's fully automated production ALD equipment Morpher and Sprinter, and it will be implemented in all future PICOSUN[®] ALD tool platforms.

PICOSUN[®]

PicoOSTM

machine interface.

PicoOS[™] is Picosun's own, proprietary full stack operating system and process control

software, designed to enable unified control of PICOSUN[®] ALD cluster systems via one common human-

> PicoOS[™] combines individual ALD module, wafer handling and transfer system, and instrumentation control under one common graphical HMI (human-machine interface). This ensures easy, intuitive and user-friendly operation, maintenance, and configuration of the whole PICOSUN[®] ALD cluster. PicoOS[™] enables full factory integration via SECS-II/GEM protocol.

> PicoOS[™] is built around data. It provides process data logging down to 20 ms rate and all available information is stored in real-time in an easily accessible database, from where it can be exported for further analysis. Maintenance procedures are sped up by specific clean-up and maintenance sequences inbuilt in the software.

PicoOS[™] has freely configurable and scalable editor for creation and storage of ALD process recipes and processing jobs, and recipes can be edited or new ones created any time during the ALD system operation. Configurable user levels and safety logic, instrumentation and interlocks guarantee safe use in day-to-day operations, and allow full access for tool management in maintenance situations.

Unified control of the whole ALD cluster via one user interface.

Please feel free to contact us for more information or a quotation!

- Integrated common HMI for the scheduler, process modules, wafer handling system and instrumentation
- Graphical interface for intuitive operation, maintenance and configuration
- Freely configurable and scalable editor for ALD process recipes and processing jobs
- Recipes can be edited/created any time during tool operation
- Automatic substrate handling and processing
- Wafer mapping
- Equipment control and substrate transfer interface for module integrations
- Process data logging down to 20 ms rate; trend data can be exported
- Full alarm and event logging with one common event log for the whole platform
- Clean-up and maintenance sequences to speed up maintenance
- Safety logic, safety instrumentation and interlocks for safe operation
- SECS-II/GEM support
- EtherCAT based communication for MFCs and MFMs
- Wide array of host connections e.g. OPC-UA (not limited to SECS-GEM)
- Designed keeping in mind future advancements: AI, IoT, Industry 4.0
- Access rights for different user levels
- Enhanced recovery features



THE PRINCIPLE OF ALD



Introduction of molecules containing element A.

Adsorption of the molecules on the surface.



Introduction of molecules containing element B and reaction with element A on the surface.



Completion of one monolayer of compound AB.

Repeat cycle till desired film thickness is reached.



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This technology is protected via granted patents or is the subject of pending patent applications.